IPC ASSOCIATION CO ELECTRONICS IN	Material Comp © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Mfg Informat	tion		
upplier Ir	nformation				·										
Company nar	me*	Company unique ID			Ţ	Unique ID Authority					Response Date*				
nsemi											2024-	2024-05-12			
Contact Name	ne	Title - Contact			I	Phone - Contact*				Emai	Email - Contact*				
Product-Env	y-Stewards		Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
uthorized R	Representative*	Title - Representative			I	Phone - Representative*				Emai	Email - Representative*				
Product-Env	y-Stewards	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
Re	Requester Item Number Mfr It		tem Number Mfr Item Name				Effective Date	ate Version Manufacturing Site		e	Weight*	UOM	Unit Type		
		LC88FC2H0AVUTE- 16bit(FROM512KB,F		B,RAM24KB	3)	2024-05-12		PHM			500.0	mg	Each		
Ianufactu	iring Proccess Informa	ation													
Tei	Terminal Plating / Grid Array Material Te			Terminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature   Max Time at F		Peak Tempe	erature Num	ber of Reflow Cy	cles			
contains Bi		CU Alloy 3		1		260		С	30	sec	conds 3				
omments															
<b>ITENTION</b>	N: MSL 3 Rated item requir	es Bake and I	ry Pack (after	electrical test)						•			•		
or more info	ormation regarding materia	l composition	please refer to	page 3		•	•		•	_		•	_		

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its part and the company acknowledges that Company and the Supplier share provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.22	mg	Supplier	Silicon (Si)	7440-21-3		6.1758	mg
			Supplier	Polyimide	Proprietary Data		0.0442	mg
Die Attach	1.5	mg	Supplier	Silver (Ag)	7440-22-4		1.065	mg
			Supplier	Epoxy resins	129915-35-1		0.435	mg
Lead Frame	150.94	mg	Supplier	Silver (Ag)	7440-22-4		0.9358	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1875	mg
			Supplier	Iron (Fe)	7439-89-6		3.5251	mg
			Supplier	Copper (Cu)	7440-50-8		146.1679	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1238	mg
Mold Compound-Black	336.44	mg		Phenolic Resin	proprietary data		16.822	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		9.4203	mg
			Supplier	Carbon Black (C)	1333-86-4		3.3644	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		10.0932	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		269.152	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		26.9152	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.6729	mg
Plating	0.5	mg	В	Bismuth (Bi)	7440-69-9		0.003	mg
			Supplier	Tin (Sn)	7440-31-5		0.497	mg
Wire Bond	4.4	mg	Supplier	Palladium (Pd)	7440-05-3		0.044	mg
			Supplier	Gold (Au)	7440-57-5		4.356	mg